

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	3855	250/370.01,370.08-370.14.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 10:38
S2	4583	257/431,435,443,448.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 10:52
S3	8340	S1 S2	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 10:52
S4	8	(puhakka-kimmo   benson-lain). in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 10:53

S5	8	(puhakka-kimmo-\$   puhaka-kimmo   benson-lain).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 10:54
S6	8	(puhakka-kimmo-\$   puhaka-kimmo-\$   benson-lain).in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 10:54
S7	5	"556820".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 11:09
S8	1	10/532119	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 11:24
S9	3855	250/370.01,370.08-370.14.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:44

S10	4583	257/431,435,443,448.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:44
S11	8340	S9 S10	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:44
S12	30427	via with electrode with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:45
S13	10251	(element pixel) with substrate with (bump bond)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:48
S14	116	S11 and S13	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:48

S15	921383	(pixel detector array sensor) with (circuit\$2 PCB board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:51
S16	20784	(pixel detector array sensor) with (circuit\$2 PCB board) with (bumps balls)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:51
S17	196	S11 and S16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:51
S18	34	S17 and (via hole) with substrate with (through)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:52
S20	24	S17 and (via hole) with substrate near3 (through)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:53

S21	17	S17 and (via hole) with (pcb circuit\$2 board) near3 (through)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:54
S22	18	S17 and (via hole) with (electronics circuit\$2 process\$3) near (board substrate) with (through)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:58
S23	58	S11 and (via hole) with (electronics circuit\$2 process\$3) near (board substrate) with (through)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 13:58
S24	235	250/370.13.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:06
S25	31	(pixel detector array sensor) with (circuit\$2 PCB board) with (bumps balls) and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:06

S26	89	chen-henry.in.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:12
S27	9374	solder adj mask	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:12
S28	3	S26 and S27	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:12
S29	56	("20010035497"   "20020066531"   "20020182716"   "20030173523"   "20070158574"   "5100767"   "5368882"   "5677539"   "5905264"   "5933706"   "6034373"   "6037595"   "6043106"   "6046068"   "6069360"   "6121622"   "6175120"   "6215123"   "6329658"   "6333504"   "6333504"   "6410922"   "6510195"   "6524966"   "6694172"   "6765213"   "6765213"   "6781132"   "7038288"   "7223981").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:13

S30	37	(pixel detector array sensor) with (circuit\$2 PCB board read \$1out chip) with (bumps balls) and S24	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:18
S32	1433	(circuit\$2 wiring board PCB PWB read\$1out) with (via holes) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:20
S33	350	(read\$1out) with (via holes) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:21
S34	53	(read\$1out) with (via holes) with (board substrate) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:21
S35	24	(read\$1out) with (via holes) near3 (board substrate) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:22

S36	29	(read\$1out) with (via holes channel) near3 (board substrate) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 14:35
S37	505	(readout read\$1out) with (via holes channel) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:04
S38	107	(readout read\$1out) with (via holes channel) with through and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:04
S39	18	(readout read\$1out) with (via holes channel) with through with substrate and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:05
S40	15	S24 AND read\$1out with vias	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:08



S41	0	S24 AND read\$1out with through near substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:09
S42	0	S24 AND read\$1out with through near3 substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:09
S43	8	S24 AND read\$1out with hole	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:10
S44	59	S11 and read\$1out with substrate with (hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:11
S45	48	S11 and read\$1out with substrate with (conduct\$3 near2 hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:12

S46	1	S11 and read\$1out with mount with (conduct\$3 near2 hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:16
S47	5	S11 and read\$1out with mount \$3 with (conduct\$3 near2 hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:16
S48	3	250/338.1-353.ccls. and read \$1out with mount\$3 with (conduct\$3 near2 hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:18
S49	42	250/338.1-353.ccls. and (circuit \$2 read\$1out) with mount\$3 with (conduct\$3 near2 hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:19
S50	45	S11 and (circuit\$2 read\$1out) with mount\$3 with (conduct\$3 near2 hole via through near2 substrate)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:19

S51	8	S11 and tile with (array detector pixel) with substrate with read \$1out	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 15:24
S52	1	read\$1out adj (circuit\$2 board) with mount and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:35
S53	20	read\$1out adj (circuit\$2 board) with mount\$3 and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:36
S54	22	read\$1out adj (circuit\$2 board) with (housing mount\$3) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:36
S55	42	read\$1out adj (circuit\$2 board) with (support\$3 housing mount \$3) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:36

S56	59	read\$1out adj (circuit\$2 board) with (support\$3 housing carrier mount\$3) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:37
S57	478	read\$1out adj (circuit\$2 substrate board) and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:45
S58	18	S57 and flip\$1chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:45
S59	11	read\$1out with (securing mount \$3) with support\$3 and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:48
S60	13	read\$1out with (securing mount \$3) with (mount support\$3) with via	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:52

S61	0	read\$1out with (securing mount \$3) with (mount support\$3) with conduct\$3 adj (opening hole pathway)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 17:54
S62	338	read\$1out with (securing mount \$3 support\$3) with (opening hole pathway)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 18:06
S63	7	S62 and S11	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/02 18:07
S64	112	read\$1out WITH mount\$3 WITH (printed adj (circuit wiring adj board) PCB PWB)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 10:32
S65	3865	250/370.01,370.08-370.14.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 10:32

S66	4585	257/431,435,443,448.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 10:32
S67	8352	S65 S66	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 10:32
S68	21	S64 and S67	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 10:33
S69	4	(US-20080093560-\$ or US-20030155516-\$).did. or (US-5962909-\$ or US-6403964-\$).did.	US-PGPUB; USPAT	OR	ON	2009/04/07 14:05
S70	4	S69 and via	US-PGPUB; USPAT	OR	ON	2009/04/07 14:06
S71	3865	250/370.01,370.08-370.14.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:14

S72	4585	257/431,435,443,448.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:14
S73	8352	S71 S72	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:14
S74	18223	"257".clas. and via adj (passage hole channel)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:15
S75	277	"257".clas. and via adj (passage hole channel) same ((insulat\$3 shield\$3) with ground)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:16
S76	3	S73 and via adj (passage hole channel) same ((insulat\$3 shield \$3) with ground)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:16

S77	525	via adj (passage hole channel) with ((insulat\$3 shield\$3) with ground)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:17
S79	181	"257".clas. and via adj (passage hole channel) with ((insulat\$3 shield\$3) with ground)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:18
S80	93	"257".clas. and via with substrate with ((insulat\$3 shield\$3) with ground) with conductive	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:53
S81	0	"257".clas. and via with substrate with insulat\$3 with ground with conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:54
S82	2	"257".clas. and via with substrate same insulat\$3 with ground same conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:54



S83	2	"257".clas. and via same insulat\$3 with ground same conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:54
S84	41	"257".clas. and via and insulat\$3 with ground and conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:55
S85	9	"257".clas. and via adj (hole channel passage) and insulat\$3 with ground and conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:55
S86	11	via adj (hole channel passage) and insulat\$3 adj (layer film) with ground and conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:58
S87	12	via adj (hole channel passage) and insulat\$3 adj (layer film) with ground\$2 and conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 14:58

S88	0	via adj (hole channel passage) with insulat\$3 adj (layer film) with ground\$2 and conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:02
S89	123	via with insulat\$3 adj (layer film) and conductive adj shield \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:02
S90	25	via with insulat\$3 adj (layer film) same conductive adj shield \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:03
S92	66	via near3 conductive adj shield \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:03
S94	55	S92 and insulat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:04

S95	24	via with substrate with conductive adj shield\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:05
S96	5	(US-20080093560-\$ or US- 20030155516-\$).did. or (US- 5962909-\$ or US-6403964-\$ or US-6952042-\$).did.	US-PGPUB; USPAT	OR	ON	2009/04/07 15:28
S97	625	conductive adj shield\$3 with potential	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:28
S100	2	conductive adj shield\$3 with potential and S96	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:29
S101	56	faraday adj shield\$3 with via	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:30
S102	2	faraday adj shield\$3 with via with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/07 15:51

S103	2	"20020130266".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 10:09
S104	3865	250/370.01,370.08-370.14.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:18
S105	4585	257/431,435,443,448.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:18
S106	8352	S104 S105	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:18
S107	1128	S106 and (photo\$1lithograph\$2 lithograph\$2)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:19

S108	68	S106 and (photo\$1lithograph\$2 lithograph\$2) with via	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:19
S109	11	S106 and (photo\$1lithograph\$2 lithograph\$2) with via adj hole	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:19
S110	8	S109 and photo\$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:20
S111	36	S108 and photo\$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:24
S112	27	S106 and (photo\$1lithograph\$2 lithograph\$2) with etch\$3 with via	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:33

S113	7	S106 and (photo\$1lithograph\$2 lithograph\$2) with etch\$3 with via with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:33
S114	1	S106 and (photo\$1lithograph\$2 lithograph\$2) same etch\$3 with via adj hole with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:48
S115	5	S106 and etch\$3 with via adj hole with substrate	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/08 14:48
S116	3865	250/370.01,370.08-370.14.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:23
S117	4586	257/431,435,443,448.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:23

S118	8353	S116 S117	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:23
S119	5	method with etch\$3 with via adj hole and S118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:24
S120	1755	method with etch\$3 with via adj hole and "257".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:26
S121	21	method with etch\$3 with via adj hole with substrate same (photo \$1lithograph\$2 lithograph\$2) and (photo\$1resist\$3) and "257".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:27
S122	2	method with etch\$3 with via adj hole with substrate same (photo \$1lithograph\$2 lithograph\$2) same (photo\$1resist\$3) same mask\$3 and "257".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:31

S123	8	method with etch\$3 with via adj hole with substrate same (photo \$1lithograph\$2 lithograph\$2) same (photo\$1resist\$3) same mask\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:36
S124	87	method with etch\$3 with via adj hole with substrate same (photo \$1resist\$3) same mask\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:37
S125	61	S124 and "257".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 09:37
S126	8	S116 and photo\$1resist\$3 with (adher\$3 adhesive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:05
S127	15	S116 and (adher\$3 adhesive) with (detector substrate) with read\$1out	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:22



S128	15	S116 and (adher\$3 adhesive) with (detector substrate) with (flip\$1chip read\$1out)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:28
S129	21	S116 and (adher\$3 adhesive) with (detector substrate) with (flip\$1chip electronic\$2 read \$1out)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:29
S130	11	S116 and (adher\$3 adhesive) with (anode electrode) with (epoxy photo\$1resist\$3 mask \$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:33
S131	56	("20010035497"   "20020066531"   "20020182716"   "20030173523"   "20070158574"   "5100767"   "5368882"   "5677539"   "5905264"   "5933706"   "6034373"   "6037595"   "6043106"   "6046068"   "6069360"   "6121622"   "6175120"   "6215123"   "6329658"   "6333504"   "6333504"   "6410922"   "6510195"   "6524966"   "6694172"   "6765213"   "6765213"   "6781132"   "7038288"   "7223981").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:35

S132	0	S131 and (adher\$3 adhesive) with (anode electrode)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:36
S133	8	S131 and (adher\$3 adhesive)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:36
S134	14120	fill\$3 with (electrode anode) with contact	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:39
S135	21	fill\$3 with (electrode anode) with contact and S116	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 11:39
S136	0	S116 and (adher\$3 adhesive) with (anode electrode) with photo\$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:00

S137	0	S116 and (adher\$3 adhesive) with read\$1out with photo \$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:00
S138	5	S116 and (adher\$3 adhesive) with substrate with photo\$1resist \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:00
S139	1	S116 and (adher\$3 adhesive) with epoxy near3 photo\$1resist \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:01
S140	3	S116 and (adher\$3 adhesive) with epoxy with photo\$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:02
S141	3	S118 and (adher\$3 adhesive) with epoxy with photo\$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:02

S142	15	S118 and (adher\$3 adhesive) with photo\$1resist\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:03
S143	34	thickness near3 substrate with via adj (hole channel passage) with thin\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/04/09 12:33

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